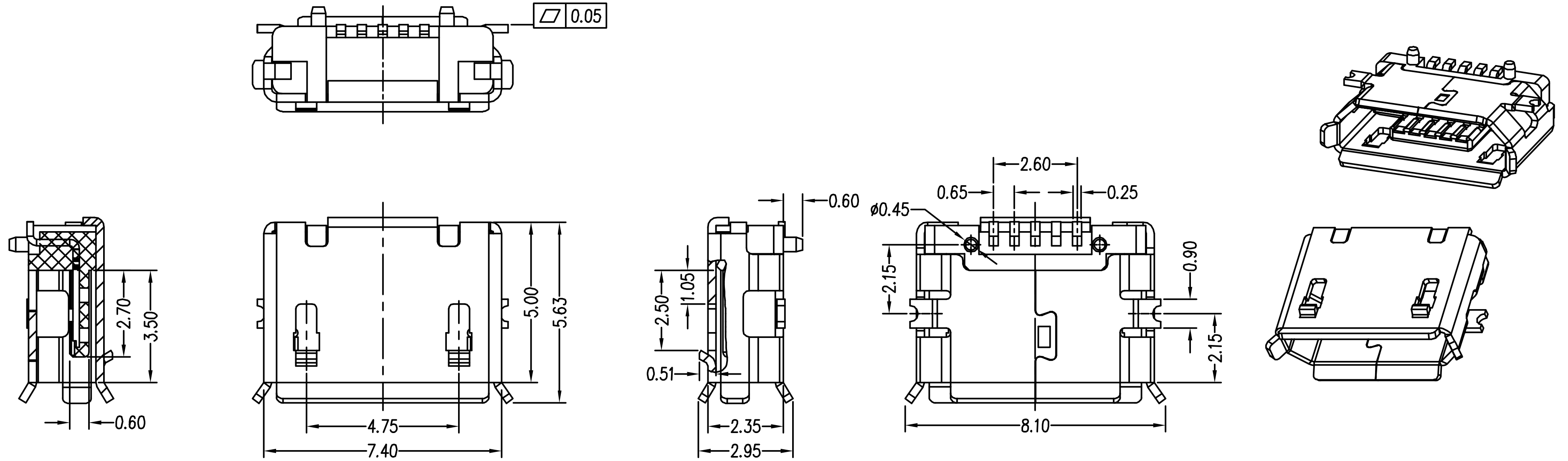
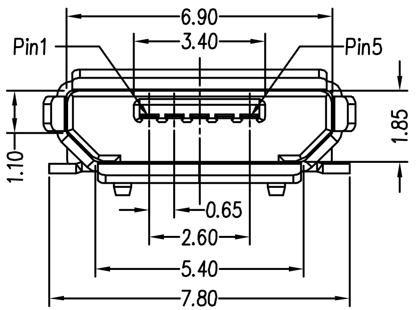
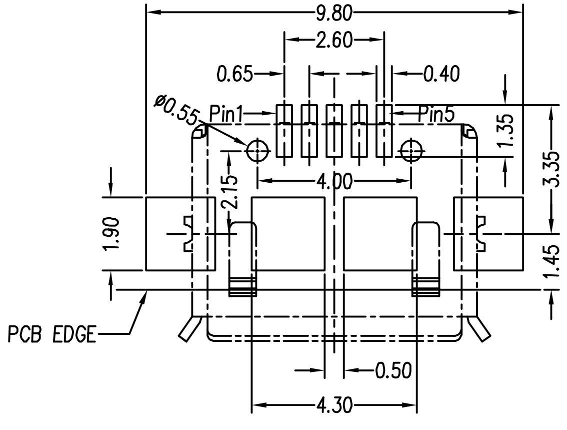
REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD







RECOMMANDED PCB LAYOUT

Note:
1.Material:
1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
1.2 Contact: copper alloy,t=0.20mm
1.3 Shell: copper alloy,t=0.25mm
2.Specification:
2.1 Current rating: 1 A Max.
2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
2.3 Contact resistance: 50 mΩ Max.
2.4 Insulation resistance: 100 MΩ Min.
2.5 Total mating force: 3.57 Kgf Max.
2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extration cycles
2.7 Temperature range: −30°C~80°C

No.	Name	Q'ty	Finish
3	Shell	1	N/A
2	Contact	5	N/A
1	Housing	1	N/A

PART NO: 1-MD05SMXXX-01
MODEL NO:
UNIT: mm
SIZE: A4
TOLERANCE UNSPECIFIED

.x	±0.38
.xx	±0.25
.xxx	±0.13
ANG.	±2°

MATERIAL: SEE NOTE
FINSH: SEE NOTE
COLOR: SEE NOTE
DR: ???
CHK:
APP:

深圳市精拓金电子有限公司

TITLE: Micro usb 5s B Type Smt有脚柱
CUSTOMER DRAWING
DWG NO: A055
REV: A
SCALE: 1:1
SHEET: 2009/04/21